CH03-FB - 3FF MICRO SIM CARD CONNECTOR SMT, SLIDE IN TYPE, WITHOUT SWITCH, WITH HALF COVER, 6 OR 8 CONTACTS

FEATURES:
1. GENERAL CHARACTERISTICS
   - DIMENSIONS: 13.44 x 13.44 x 2.40 mm
   - WEIGHT: APPROX. 0.5g
   - CONTACT FRICTION TECHNOLOGY

2. MECHANICAL CHARACTERISTICS
   - MATERIAL: THERMOPLASTIC UL 94V-0
   - CONTACT MATERIAL: PHOSPHOR BRONZE

3. ELECTRICAL CHARACTERISTICS
   - NUMBER OF CONTACTS: 6, 8 PINS (OPTIONAL)
   - CONTACT RESISTANCE: ≤ 55 mΩ RMS TYP., 100 mΩ RMS MAX.
   - INSULATION RESISTANCE: > 1000MΩ RMS / 500V DC

4. SOLENOID CHARACTERISTICS
   - VOLTAGE: 500V AC RMS, 1 MINUTE

5. ENVIRONMENTAL CHARACTERISTICS
   - OPERATING TEMPERATURE: -40°C to 85°C
   - OPERATING HUMIDITY: 10% - 95% RH

NOTES:
1. ACCEPTABLE SIM CARD SIZE SHOULD MEET GSM 11.11 SPECIFICATION REQUIREMENT.

THICKNESS: 0.76 ± 0.08 MM MICRO SIM CARD

HOW TO ORDER

CH03 - FB X X 0 - 0 BR

NO. OF CONTACTS
06 OR 08

PACKAGING OPTIONS
R = TAPE & REEL (500PCS/REEL)

Type: CH03-FB
NOTES:
1. REEL DIA: 33CM.
2. 900PCS PER REEL, GROSS WEIGHT: 0.77KG.
3. 10 REELS PER FULL CARTON, GROSS WEIGHT: 7.7KG.